3.3V LVTTL/LVCMOS to **Differential LVECL Translator**

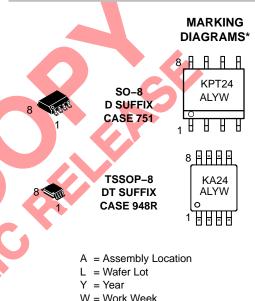
The MC100EPT24 is a LVTTL/LVCMOS to differential LVECL translator. Because LVECL levels and LVTTL/LVCMOS levels are used, a -3.3 V, +3.3 V and ground are required. The small outline 8-lead package and the single gate of the EPT24 makes it ideal for those applications where space, performance, and low power are at a premium.

- 350 ps Typical Propagation Delay
- Maximum Frequency > 1.0 GHz Typical
- The 100 Series Contains Temperature Compensation
- Operating Range: $V_{CC} = 3.0 \text{ V}$ to 3.6 V; $V_{EE} = -3.6 \text{ V to } -3.0 \text{ V; GND} = 0 \text{ V}$
- PNP LVTTL Inputs for Minimal Loading
- Q Output Will Default HIGH with Input Open



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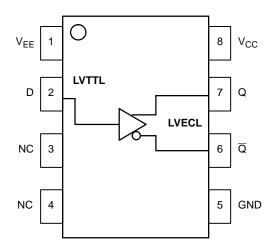


W = Work Week

*For additional information, see Application Note AND8002/D

ORDERING INFORMATION

Device	Package	Shipping
MC100EPT24D	SO-8	98 Units / Rail
MC100EPT24DR2	SO-8	2500 Tape & Reel
MC100EPT24DT	TSSOP-8	100 Units / Rail
MC100EPT24DTR2	TSSOP-8	2500 Tape & Reel



PIN DESCRIPTION

PIN	FUNCTION
Q, Q	Differential LVECL Outputs
D	LVTTL Input
V _{CC}	Positive Supply
GND	Ground
V _{EE}	Negative Supply
NC	No Connect

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

ATTRIBUTES

Characteristics		Value
Internal Input Pulldown Resistor		N/A
Internal Input Pullup Resistor		N/A
ESD Protection	Human Body Model Machine Model narged Device Model	> 4 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of D	rypack (Note 1)	Level 1
Flammability Rating Oxygen Index		UL-94 code V-0 A 1/8" 28 to 34
Transistor Count		181 Devices
Meets or exceeds JEDEC Spec EIA/JESD78	IC Latchup Test	

^{1.} For additional information, see Application Note AND8003/D.

MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	Positive Power Supply	GND = 0 V	$V_{EE} = -3.3 \text{ V}$	3.8	V
V _{EE}	Negative Power Supply	GND = 0 V	V _{CC} = +3.3 V	-3.8	V
V _{IN}	Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	0 to V _{CC}	٧
l _{out}	Output Current	Continuous Surge		50 100	mA mA
TA	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W
θ _{JC}	Thermal Resistance (Junction to Case)	std bd	8 TSSOP	41 to 44	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

^{2.} Maximum Ratings are those values beyond which device damage may occur.

LVTTL INPUT DC CHARACTERISTICS V_{CC} = 3.3 V, V_{EE} = -3.6 V to -3.0 V, GND= 0.0 V; T_{A} = -40°C to 85°C

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
I _{IH}	Input HIGH Current	V _{IN} = 2.7 V			20	μΑ
I _{IHH}	Input HIGH Current	V _{IN} = 6.0 V			100	μΑ
I _{IL}	Input LOW Current	V _{IN} = 0.5 V			-0.6	mA
V _{IK}	Input Clamp Diode Voltage	$I_{IN} = -18 \text{ mA}$			-1.2	V
V _{IH}	Input HIGH Voltage		2.0			V
V _{IL}	Input LOW Voltage				0.8	V

NECL OUTPUT DC CHARACTERISTICS V_{CC} = 3.3 V, V_{EE} = -3.3 V, GND= 0.0 V (Note 3)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{OH}	Output HIGH Voltage (Note 4)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1030	-895	mV
V _{OL}	Output LOW Voltage (Note 4)	-1945	-1820	-1695	-1945	-1820	-1695	-1945	-1820	-1695	mV
I _{CC}	Power Supply Current		2.0	4.0		2.0	4.0		2.0	4.0	mA
I _{EE}	Power Supply Current	20	30	38	20	30	38	20	30	38	mA

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 Ifpm is maintained.

- 3. Output levels will vary 1:1 with GND. V_{EE} can vary \pm 0.3 V. 4. Outputs are terminated through a 50 ohm resistor to GND-2 volts.

AC CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, V_{EE} = -3.6 V to -3.0 V, GND= 0.0 V (Note 5)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Frequency (See Figure 2. F _{max} /JITTER)))	>1			> 1			> 1		GHz
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential (Note 6)	300	500	800	300	530	800	300	560	800	ps
t _{JITTER}	Cycle-to-Cycle Jitter (See Figure 2. F _{max} /JITTER)		0.2	< 1		0.2	< 1		0.2	< 1	ps
t _r t _f	Output Rise/Fall Times Q, Q (20% – 80%)	70	125	170	80	130	180	100	150	200	ps

- 5. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 ohms to GND-2.0 V.
 6. Specifications for standard TTL input signal.

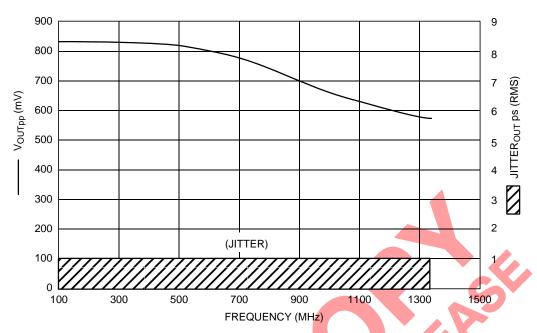


Figure 2. F_{max}/Jitter

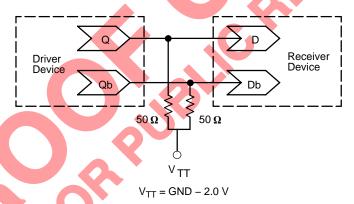


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020 – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1404 – ECLinPS Circuit Performance at Non–Standard V_{IH} Levels

AN1405 – ECL Clock Distribution Techniques

AN1406 – Designing with PECL (ECL at +5.0 V)

AN1504 – Metastability and the ECLinPS Family

AN1568 – Interfacing Between LVDS and ECL

AN1650 – Using Wire–OR Ties in ECLinPS Designs

AN1672 - The ECL Translator Guide

AND8001 - Odd Number Counters Design

AND8002 - Marking and Date Codes

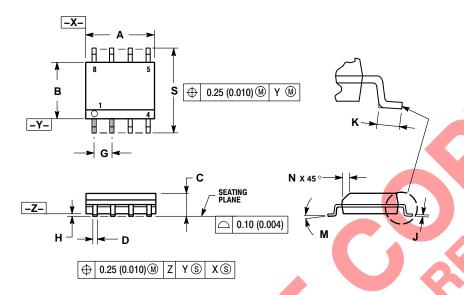
AND8009 – ECLinPS Plus Spice I/O Model Kit

AND8020 – Termination of ECL Logic Devices

For an updated list of Application Notes, please see our website at http://onsemi.com.

PACKAGE DIMENSIONS

SO-8 D SUFFIX PLASTIC SOIC PACKAGE CASE 751-07 **ISSUE AA**

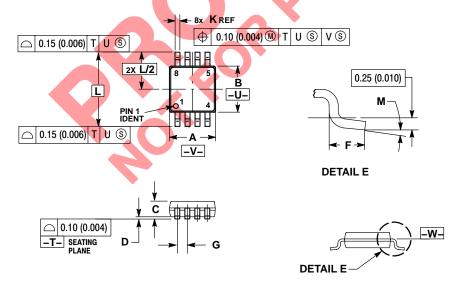


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PEF SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIN	IETERS	INCHES						
DIM	MIN	MAX	MIN	MAX					
Α	4.80	5.00	0.189	0.197					
В			0.150	0.157					
C			0.053	0.069					
D	0.33	0.51	0.013	0.020					
G	1.2	7 BSC	0.050 BSC						
Н	0.10 0.25		0.004	0.010					
J	0.19	0.25	0.007	0.010					
K	0.40	1.27	0.016	0.050					
M	M 0° 8°		0 °	8 °					
N	0.25	0.50	0.010	0.020					
S	5.80	6.20	0.228	0.244					

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 ISSUE A



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 114.3M, 1902.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

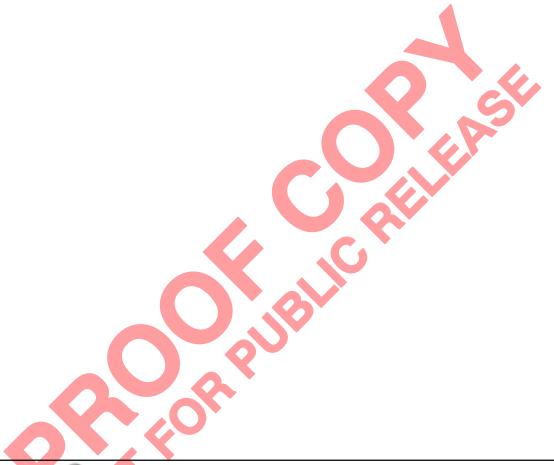
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10 0.1		0.122	
C	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25 0.40		0.010 0.016		
L	4.90	BSC	0.193	BSC	
M	0° 6°		0°	6°	

Notes





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